

CY7C1020V



#### **Features**

- 3.3V operation (3.0V 3.6V)
- High speed
  - $-t_{AA} = 10 \text{ ns}$
- · Low active power
  - 540 mW (max., 12 ns)
- · Very Low standby power
  - 330 μW (max., "L" version)
- Automatic power-down when deselected
- Independent Control of Upper and Lower bytes
- · Available in 44-pin TSOP II and 400-mil SOJ

#### **Functional Description**

The CY7C1020V is a high-performance CMOS static RAM organized as 32,768 words by 16 bits. This device has an automatic power-down feature that significantly reduces power consumption when deselected.

Writing to the device is accomplished by taking chip enable (CE) and write enable (WE) inputs LOW. If byte low enable

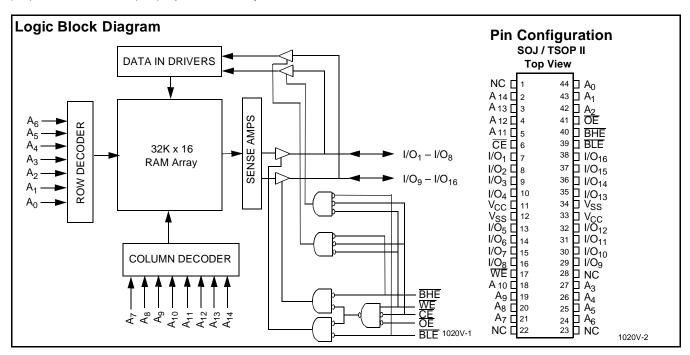
# 32K x 16 Static RAM

(BLE) is LOW, then data from I/O pins (I/O<sub>1</sub> through I/O<sub>8</sub>), is written into the location specified on the address pins (A<sub>0</sub> through A<sub>14</sub>). If byte high enable (BHE) is LOW, then data from I/O pins (I/O<sub>9</sub> through I/O<sub>16</sub>) is written into the location specified on the address pins ( $A_0$  through  $A_{14}$ ).

Reading from the device is accomplished by taking chip enable (CE) and output enable (OE) LOW while forcing the write enable (WE) HIGH. If byte low enable (BLE) is LOW, then data from the memory location specified by the address pins will appear on I/O<sub>1</sub> to I/O<sub>8</sub>. If byte high enable (BHE) is LOW, then data from memory will appear on I/O<sub>9</sub> to I/O<sub>16</sub>. See the truth table at the back of this datasheet for a complete description of read and write modes.

The input/output pins (I/O<sub>1</sub> through I/O<sub>16</sub>) are placed in a high-impedance state when the device is deselected (CE HIGH), the outputs are disabled (OE HIGH), the BHE and BLE are disabled (BHE, BLE HIGH), or during a write operation (CE LOW, and  $\overline{\text{WE}}$  LOW).

The CY7C1020V is available in standard 44-pin TSOP type II and 400-mil-wide SOJ packages.



#### **Selection Guide**

		7C1020V-10	7C1020V-12	7C1020V-15	7C1020V-20
Maximum Access Time (ns)		10	12	15	20
Maximum Operating Current (mA)		130	120	110	100
	L	100	90	80	70
Maximum CMOS Standby Current (mA)		1	1	1	1
	L	0.1	0.1	0.1	0.1



### **Maximum Ratings**

(Above which the useful life may be impaired. For user guidelines, not tested.) Storage Temperature .....-65°C to +150°C Ambient Temperature with Supply Voltage on  $V_{CC}$  to Relative  $GND^{[1]}$  .... –0.5V to +4.6V DC Voltage Applied to Outputs in High Z State<sup>[1]</sup>.....-0.5V to V<sub>CC</sub> +0.5V DC Input Voltage<sup>[1]</sup>.....-0.5V to V<sub>CC</sub> +0.5V

Current into Outputs (LOW)	20 mA
Static Discharge Voltage(per MIL-STD-883, Method 3015)	>2001V
Latch-Up Current	>200 mA

#### **Operating Range**

Range	Ambient Temperature <sup>[2]</sup>	V <sub>CC</sub>		
Commercial	0°C to +70°C	3.0V - 3.6V		
Industrial	-40°C to +85°C	3.0V - 3.6V		

## **Electrical Characteristics** Over the Operating Range

					20V-10	7C102	20V-12	
Parameter	Description	Test Conditions	Min.	Max.	Min.	Max.	Unit	
V <sub>OH</sub>	Output HIGH Voltage	$V_{CC} = Min., I_{OH} = -4.0 \text{ mA}$	2.4		2.4		V	
V <sub>OL</sub>	Output LOW Voltage	$V_{CC} = Min., I_{OL} = 8.0 \text{ mA}$			0.4		0.4	V
V <sub>IH</sub>	Input HIGH Voltage		2.0	V <sub>CC</sub> + 0.3V	2.0	V <sub>CC</sub> + 0.3V	V	
V <sub>IL</sub>	Input LOW Voltage <sup>[1]</sup>			-0.5	0.8	-0.5	0.8	V
I <sub>IX</sub>	Input Load Current	$GND \le V_1 \le V_{CC}$	$GND \le V_1 \le V_{CC}$			-1	+1	μΑ
I <sub>OZ</sub>	Output Leakage Current	$GND \le V_1 \le V_{CC}$ , Output Disab	oled	-2	+2	-2	+2	μΑ
I <sub>CC</sub>	V <sub>CC</sub> Operating Supply Current	V <sub>CC</sub> = Max.,			130		120	mA
		$I_{OUT} = 0 \text{ mÅ},$ $f = f_{MAX} = 1/t_{RC}$	L		100		90	mA
I <sub>SB1</sub>	Automatic CE	Max. V <sub>CC</sub> , <del>CE</del> ≥ V <sub>IH</sub>			15		15	mA
	Power-Down Current —TTL Inputs	$V_{IN} \ge V_{IH}$ or $V_{IN} \le V_{IL}$ , $f = f_{MAX}$	L		7		7	mA
I <sub>SB2</sub>	Automatic CE	Max. V <sub>CC</sub> ,			1		1	mA
	Power-Down Current —CMOS Inputs	$\overline{CE} \ge V_{CC} - 0.3V$ , $V_{IN} \ge V_{CC} - 0.3V$ , or $V_{IN} \le 0.3V$ , f=0	L		100		100	μА

#### Notes:

- 1.  $V_{IL}$  (min.) = -2.0V for pulse durations of less than 20 ns. 2.  $T_A$  is the "instant on" case temperature.



## **Electrical Characteristics** Over the Operating Range (continued)

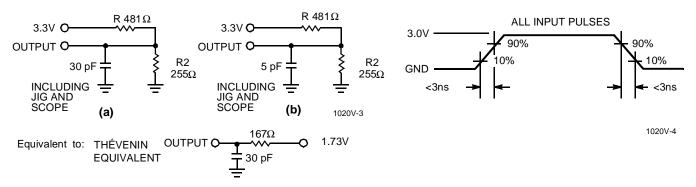
				7C102	20V-15	7C102		
Parameter	Description	Test Conditions		Min.	Max.	Min.	Max.	Unit
V <sub>OH</sub>	Output HIGH Voltage	$V_{CC} = Min., I_{OH} = -4.0 \text{ mA}$	2.4		2.4		V	
V <sub>OL</sub>	Output LOW Voltage	$V_{CC} = Min., I_{OL} = 8.0 \text{ mA}$			0.4		0.4	V
V <sub>IH</sub>	Input HIGH Voltage			2.0	V <sub>CC</sub> + 0.3V	2.0	V <sub>CC</sub> + 0.3V	V
V <sub>IL</sub>	Input LOW Voltage <sup>[1]</sup>			-0.5	0.8	-0.5	0.8	V
I <sub>IX</sub>	Input Load Current	$GND \le V_I \le V_{CC}$	$GND \le V_1 \le V_{CC}$			-1	+1	μΑ
I <sub>OZ</sub>	Output Leakage Current	$GND \le V_I \le V_{CC}$ , Output Disabl	led	-2	+2	-2	+2	μΑ
I <sub>CC</sub>	V <sub>CC</sub> Operating Supply Current	V <sub>CC</sub> = Max.,			110		100	mA
		$I_{OUT} = 0 \text{ mÅ},$ $f = f_{MAX} = 1/t_{RC}$	L		80		70	mA
I <sub>SB1</sub>	Automatic CE	Max. V <sub>CC</sub> , <del>CE</del> ≥ V <sub>IH</sub>			15		15	mA
	Power-Down Current —TTL Inputs	$V_{IN} \ge V_{IH}$ or $V_{IN} \le V_{IL}$ , $f = f_{MAX}$	L		7		7	mA
I <sub>SB2</sub>	Automatic CE	Max. V <sub>CC</sub> ,			1		1	mA
	Power-Down Current —CMOS Inputs	$\overline{\text{CE}} \ge \text{V}_{\text{CC}} - 0.3\text{V}, \\ \text{V}_{\text{IN}} \ge \text{V}_{\text{CC}} - 0.3\text{V}, \\ \text{or } \text{V}_{\text{IN}} \le 0.3\text{V}, \text{f=0}$	L		100		100	μА

## Capacitance<sup>[3]</sup>

Parameter	Description	Test Conditions	Max.	Unit
C <sub>IN</sub>	Input Capacitance	$T_A = 25^{\circ}C, f = 1 \text{ MHz},$	8	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC} = 3.3V$	8	pF

#### Notes:

#### **AC Test Loads and Waveforms**



<sup>3.</sup> Tested initially and after any design or process changes that may affect these parameters.



## Switching Characteristics<sup>[4]</sup> Over the Operating Range

		7C102	20V-10	7C1020V-12		7C1020V-15		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Unit
READ CYC	LE	<b>'</b>			1			
t <sub>RC</sub>	Read Cycle Time	10		12		15		ns
t <sub>AA</sub>	Address to Data Valid		10		12		15	ns
t <sub>OHA</sub>	Data Hold from Address Change	3		3		3		ns
t <sub>ACE</sub>	CE LOW to Data Valid		10		12		15	ns
t <sub>DOE</sub>	OE LOW to Data Valid		5		6		7	ns
t <sub>LZOE</sub>	OE LOW to Low Z	0		0		0		ns
t <sub>HZOE</sub>	OE HIGH to High Z <sup>[5, 6]</sup>		5		6		7	ns
t <sub>LZCE</sub>	CE LOW to Low Z <sup>[6]</sup>	3		3		3		ns
t <sub>HZCE</sub>	CE HIGH to High Z <sup>[5, 6]</sup>		5		6		7	ns
t <sub>PU</sub>	CE LOW to Power-Up	0		0		0		ns
t <sub>PD</sub>	CE HIGH to Power-Down		12		12		15	ns
t <sub>DBE</sub>	Byte enable to Data Valid		5		6		7	ns
t <sub>LZBE</sub>	Byte enable to Low Z	0		0		0		ns
t <sub>HZBE</sub>	Byte disable to High Z		5		6		7	ns
WRITE CYC	CLE <sup>[7]</sup>							
t <sub>WC</sub>	Write Cycle Time	10		12		15		ns
t <sub>SCE</sub>	CE LOW to Write End	8		9		10		ns
t <sub>AW</sub>	Address Set-Up to Write End	7		8		10		ns
t <sub>HA</sub>	Address Hold from Write End	0		0		0		ns
t <sub>SA</sub>	Address Set-Up to Write Start	0		0		0		ns
t <sub>PWE</sub>	WE Pulse Width	7		8		10		ns
t <sub>SD</sub>	Data Set-Up to Write End	5		6		10		ns
t <sub>HD</sub>	Data Hold from Write End	0		0		0		ns
t <sub>LZWE</sub>	WE HIGH to Low Z <sup>[6]</sup>	3		3		3		ns
t <sub>HZWE</sub>	WE LOW to High Z <sup>[5, 6]</sup>		5		6		7	ns
t <sub>BW</sub>	Byte enable to end of write	7		8		9		ns

Test conditions assume signal transition time of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified  $\rm I_{OL}/I_{OH}$  and 30-pF load capacitance.

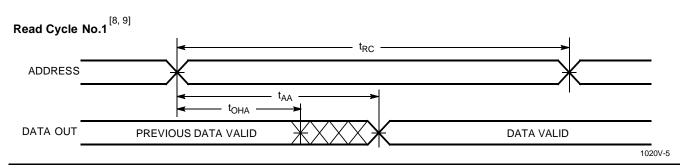
t<sub>HZOE</sub>, t<sub>HZEE</sub>, t<sub>HZEE</sub>, t<sub>HZCE</sub>, and t<sub>HZWE</sub> are specified with a load capacitance of 5 pF as in part (b) of AC Test Loads. Transition is measured ±500 mV from steady-state voltage. At any given temperature and voltage condition, t<sub>HZCE</sub> is less than t<sub>LZCE</sub>, t<sub>HZOE</sub> is less than t<sub>LZCE</sub>, take it less than t<sub>LZCE</sub>, and t<sub>HZWE</sub> is less than t<sub>LZWE</sub> for any given device. The internal write time of the memory is defined by the overlap of CE LOW, WE LOW and BHE / BLE LOW. CE, WE and BHE / BLE must be LOW to initiate a write, and the transition of these signals can terminate the write. The input data set-up and hold timing should be referenced to the leading edge of the signal that terminates the write.



## $\textbf{Switching Characteristics}^{[4]} \ \text{Over the Operating Range (continued)}$

		7C10	20V-20		
Parameter	Description	Min.	Max.	Unit	
READ CYC	ĹE	·	1	U.	
t <sub>RC</sub>	Read Cycle Time	20		ns	
t <sub>AA</sub>	Address to Data Valid		20	ns	
t <sub>OHA</sub>	Data Hold from Address Change	3		ns	
t <sub>ACE</sub>	CE LOW to Data Valid		20	ns	
t <sub>DOE</sub>	OE LOW to Data Valid		9	ns	
t <sub>LZOE</sub>	OE LOW to Low Z	0		ns	
t <sub>LZCE</sub>	CE LOW to Low Z <sup>[6]</sup>	3		ns	
t <sub>HZCE</sub>	CE HIGH to High Z <sup>[5, 6]</sup>		9	ns	
t <sub>PU</sub>	CE LOW to Power-Up	0		ns	
t <sub>PD</sub>	CE HIGH to Power-Down		20	ns	
t <sub>DBE</sub>	Byte enable to Data Valid		9	ns	
t <sub>LZBE</sub>	Byte enable to Low Z	0		ns	
t <sub>HZBE</sub>	Byte disable to High Z		9	ns	
WRITE CYC	CLE <sup>[7]</sup>	<u>.</u>		•	
t <sub>WC</sub>	Write Cycle Time	20		ns	
t <sub>SCE</sub>	CE LOW to Write End	12		ns	
t <sub>AW</sub>	Address Set-Up to Write End	12		ns	
t <sub>HA</sub>	Address Hold from Write End	0		ns	
t <sub>SA</sub>	Address Set-Up to Write Start	0		ns	
t <sub>PWE</sub>	WE Pulse Width	12		ns	
t <sub>SD</sub>	Data Set-Up to Write End	10		ns	
t <sub>HD</sub>	Data Hold from Write End	0		ns	
t <sub>LZWE</sub>	WE HIGH to Low Z <sup>[6]</sup>	3		ns	
t <sub>HZWE</sub>	WE LOW to High Z <sup>[5, 6]</sup>		9	ns	
t <sub>BW</sub>	Byte enable to end of write	12		ns	

## **Switching Waveforms**



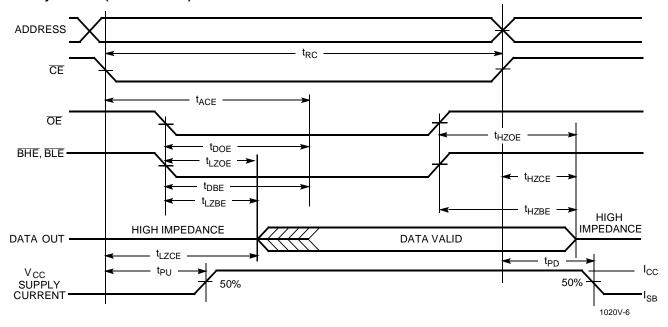
#### Notes:

- 8. Device is continuously selected. OE, CE, BHE, and/or BHE = V<sub>IL</sub>
  9. WE is HIGH for read cycle.

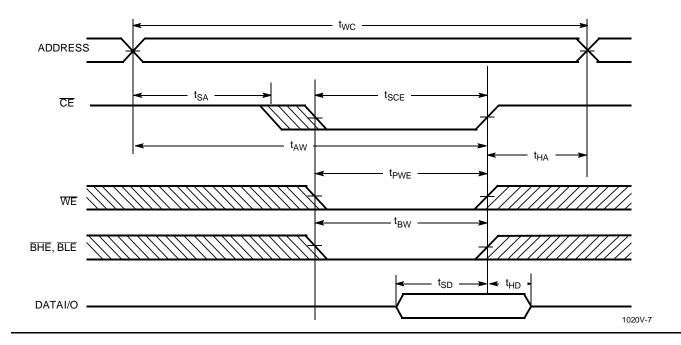


## Switching Waveforms (continued)

# Read Cycle No.2 ( $\overline{\text{OE}}$ Controlled) $^{[9, 10]}$



# Write Cycle No. 1 ( $\overline{\text{CE}}$ Controlled) [11, 12]



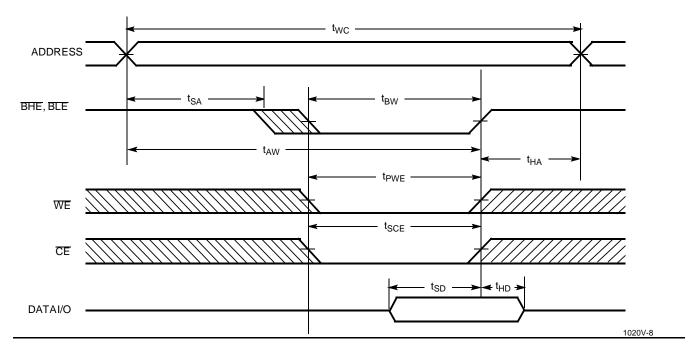
#### Notes:

- 10. Address valid prior to or coincident with CE transition LOW.
  11. Data I/O is high impedance if OE or BHE and/or BLE= V<sub>IH</sub>.
  12. If CE goes HIGH simultaneously with WE going HIGH, the output remains in a high-impedance state.

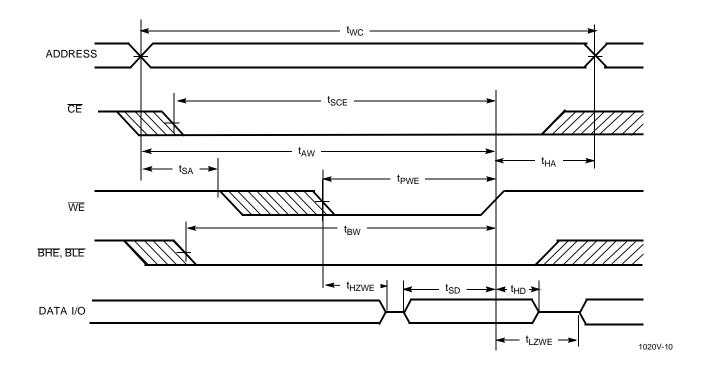


## Switching Waveforms (continued)

## Write Cycle No. 2 (BLE or BHE Controlled)



## Write Cycle No.3 (WE Controlled, OE LOW)





## **Truth Table**

CE	OE	WE	BLE	BHE	I/O <sub>1</sub> - I/O <sub>8</sub>	I/O <sub>9</sub> - I/O <sub>16</sub>	Mode	Power
Н	Х	Χ	Χ	Х	High Z	High Z	Power-Down	Standby (I <sub>SB</sub> )
L	L	Н	L	L	Data Out	Data Out	Read - All bits	Active (I <sub>CC</sub> )
			L	Н	Data Out	High Z	Read - Lower bits only	Active (I <sub>CC</sub> )
			Н	L	High Z	Data Out	Read - Upper bits only	Active (I <sub>CC</sub> )
L	Х	L	L	L	Data In	Data In	Write - All bits	Active (I <sub>CC</sub> )
			L	Н	Data In	High Z	Write - Lower bits only	Active (I <sub>CC</sub> )
			Н	L	High Z	Data In	Write - Upper bits only	Active (I <sub>CC</sub> )
L	Н	Н	Χ	Х	High Z	High Z	Selected, Outputs Disabled	Active (I <sub>CC</sub> )
L	Х	Χ	Н	Н	High Z	High Z	Selected, Outputs Disabled	Active (I <sub>CC</sub> )

## **Ordering Information**

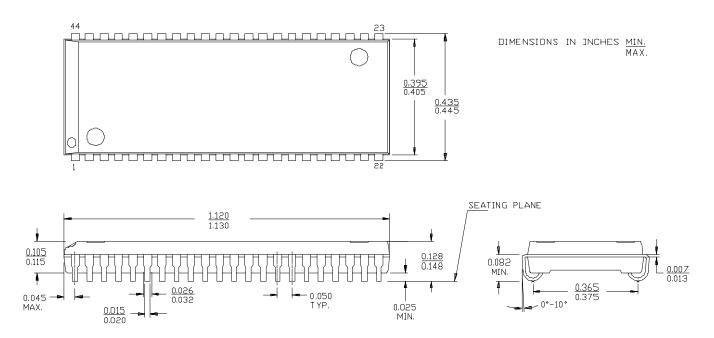
Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
10	CY7C1020V33-10VC	V34	44-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1020V33L-10VC	V34	44-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1020V33-10ZC	Z44	44-Lead TSOP Type II	Commercial
	CY7C1020V33L-10ZC	Z44	44-Lead TSOP Type II	Commercial
12	CY7C1020V33-12VC	V34	44-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1020V33L-12VC	V34	44-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1020V33-12ZC	Z44	44-Lead TSOP Type II	Commercial
	CY7C1020V33L-12ZC	Z44	44-Lead TSOP Type II	Commercial
15	CY7C1020V33-15VC	V34	44-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1020V33L-15VC	V34	44-Lead (400-Mil) Molded SOJ	Commercial
	CY7C1020V33-15ZC	Z44	44-Lead TSOP Type II	Commercial
	CY7C1020V33L-15ZC	Z44	44-Lead TSOP Type II	Commercial
	CY7C1020V33-15ZI	Z44	44-Lead TSOP Type II	Industrial
20	CY7C1020V33L-20ZC	Z44	44-Lead TSOP Type II	Commercial

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#### **Package Diagrams**

#### 44-Lead (400-Mil) Molded SOJ V34



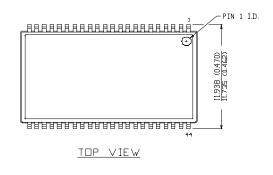
#### 44-Pin TSOP II Z44

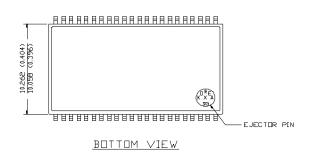
DIMENSION (N MM (INCH)

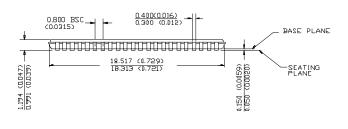
MAX

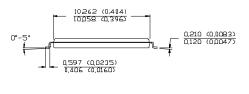
MIN

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